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(54) Title: INLET HEAD ASSEMBLY

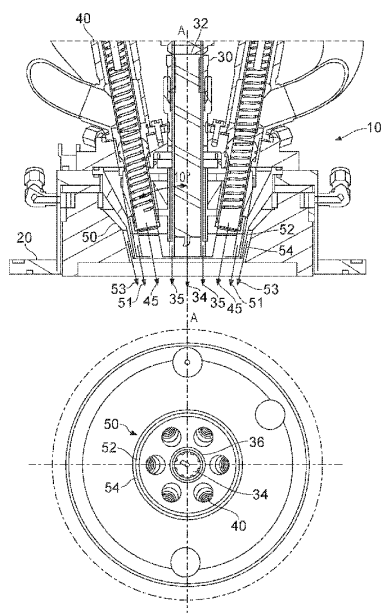


FIG. 1

(57) Abstract: An inlet head assembly for an abatement apparatus is disclosed. The inlet head assembly is for an abatement apparatus for abating an effluent stream from a semiconductor processing tool, the inlet head assembly comprises: an inlet head; a pilot nozzle extending within the inlet head and configured to supply at least one pilot combustion reagent stream to a downstream abatement chamber of the abatement apparatus; and a plurality inlet nozzles, each extending within the inlet head and configured to supply an associated effluent stream for abatement within the abatement chamber, the plurality of inlet nozzles being positioned around the pilot nozzle. In this way, the effluent streams are packed closer together around the pilot nozzle which improves the heating of the effluent stream, improving the DRE and reducing heat loss, which enables a reduction in the combustion reagents needing to be supplied.

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